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United States Patent and Trademark Office

Form PTO-1595 (Rev. 09/04)
OMB No. 0651-0027 (exp. 6/30/2005)



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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):

- 1. Sakae Koyata
- 2. Yuichi Kakizono
- 3. Tomohiro Hashii
- 4. Katsuhiko Murayama

Execution Date(s) January 25, 2006

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other _____

2. Name and address of receiving party(ies)

Name: SUMCO CORPORATION

Internal Address: _____

Street Address: 2-1, Shibaura 1-chome

City: Minato-Ku

State: Tokyo

Country: Japan

OFFICE OF PATENT RECORDS
2006 MAR 11 11:11:54
FINANCE SECTION

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)
11/345,009

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Jules E. Goldberg, Esq.

Internal Address: Reed Smith LLP

Street Address: 599 Lexington Avenue, 29th Fl

City: New York

State: New York Zip: 10022

Phone Number: (212) 521-5403

Fax Number: (212) 521-5450

Email Address: jgoldberg@reedsmith.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number 50-1529

Authorized User Name _____

9. Signature:

April 6, 2006 Date

Jules E. Goldberg, Esq.

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 5

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

04/12/2006 DRYNE
00000204 17345009

40.00

PATENT
REEL: 017772 FRAME: 0375

ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA

Whereas, I/We, Sakae Koyata

of c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereafter "Assignor") have new and useful improvements in ETCHING LIQUID FOR CONTROLLING SILICON WAFER SURFACE SHAPE AND METHOD FOR MANUFACTURING SILICON WAFER USING THE SAME which application for Letters Patent in the United States of America | | is about to be filed. | | has been filed.

And Whereas, SUMCO CORPORATION
of 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan
(hereinafter "Assignee") is/are desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor:

Now, therefore, be it known by all whom it may concern, that for good and valuable consideration (the sufficiency of which is hereby acknowledged) the Assignor has assigned, transferred and set over, and by these presents does assign, transfer and set over unto the said Assignee for the territory of the United States of America, the full and exclusive right, title, and interest in and to the said application and the invention embodied therein, as fully set forth and described in the specification.

- A. prepared and executed on _____
- B. filed in the U.S. Patent and Trademark Office under Serial No. _____

on _____ including any division, continuation, substitute or renewal application thereof, said invention, application and Letters Patent to be held and enjoyed by the said Assignee to the full end of the term for which said Letters Patent is granted, as fully and entirely as the same would have been held by the Assignor had this assignment and transfer not been made.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 25 day of Jan 20 06.

WITNESS:

INVENTOR(S):

_____	<u>Sakae Koyata</u>	<u>Sakae Koyata</u>
_____	(Name of Assignor)	(Signature of Assignor)
_____	/	/
_____	(Name of Assignor)	(Signature of Assignor)
_____	/	/
_____	(Name of Assignor)	(Signature of Assignor)
_____	/	/
_____	(Name of Assignor)	(Signature of Assignor)

ReedSmithLLP

375 Park Avenue
17th Floor
New York, NY 10152-1799
212.521.5400
Fax 212.521.5450

ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA

Whereas, I/We, Yuichi Kaizono

of c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereafter "Assignor") have new and useful improvements in ETCHING LIQUID FOR CONTROLLING SILICON
WAFER SURFACE SHAPE AND METHOD FOR MANUFACTURING SILICON WAFER USING THE SAME
which application for Letters Patent in the United States of America | | is about to be filed. | | has been filed.

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of 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan
(hereinafter "Assignee") is/are desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor:

Now, therefore, be it known by all whom it may concern, that for good and valuable consideration (the sufficiency of which is hereby acknowledged) the Assignor has assigned, transferred and set over, and by these presents does assign, transfer and set over unto the said Assignee for the territory of the United States of America, the full and exclusive right, title, and interest in and to the said application and the invention embodied therein, as fully set forth and described in the specification.

A. prepared and executed on _____

B. filed in the U.S. Patent and Trademark Office under Serial No. _____

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Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 25 day of Jan 20 06

WITNESS:

INVENTOR(S):

_____	Yuichi Kakizono	<u>Yuichi Kakizono</u>
_____	(Name of Assignor)	(Signature of Assignor)
_____	_____	/
_____	(Name of Assignor)	(Signature of Assignor)
_____	_____	/
_____	(Name of Assignor)	(Signature of Assignor)
_____	_____	/
_____	(Name of Assignor)	(Signature of Assignor)
_____	_____	/
_____	(Name of Assignor)	(Signature of Assignor)

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ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA

Whereas, I/We, Tomohiro Hashii

of c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereafter "Assignor") have new and useful improvements in ETCHING LIQUID FOR CONTROLLING SILICON WAFER SURFACE SHAPE AND METHOD FOR MANUFACTURING SILICON WAFER USING THE SAME which application for Letters Patent in the United States of America | | is about to be filed. | | has been filed.

And Whereas, SUMCO CORPORATION
of 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan
(hereinafter "Assignee") is/are desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor:

Now, therefore, be it known by all whom it may concern, that for good and valuable consideration (the sufficiency of which is hereby acknowledged) the Assignor has assigned, transferred and set over, and by these presents does assign, transfer and set over unto the said Assignee for the territory of the United States of America, the full and exclusive right, title, and interest in and to the said application and the invention embodied therein, as fully set forth and described in the specification.

A. prepared and executed on _____

B. filed in the U.S. Patent and Trademark Office under Serial No. _____

on _____ including any division, continuation, substitute or renewal application thereof, said invention, application and Letters Patent to be held and enjoyed by the said Assignee to the full end of the term for which said Letters Patent is granted, as fully and entirely as the same would have been held by the Assignor had this assignment and transfer not been made.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent for said invention to said Assignee.

In testimony whereof the Assignor has hereunto set his hand this 25 day of

Jan 20 06

WITNESS:

INVENTOR(S):

Tomohiro Hashii

Tomohiro Hashii

(Name of Assignor)

(Signature of Assignor)

(Name of Assignor)

(Signature of Assignor)

(Name of Assignor)

(Signature of Assignor)

(Name of Assignor)

(Signature of Assignor)

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(Signature of Assignor)

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ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA

Whereas, I/We, Katsuhiko Murayama

of c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereafter "Assignor") have new and useful improvements in ETCHING LIQUID FOR CONTROLLING SILICON WAFER SURFACE SHAPE AND METHOD FOR MANUFACTURING SILICON WAFER USING THE SAME which application for Letters Patent in the United States of America | | is about to be filed. | | has been filed.

And Whereas, SUMCO CORPORATION
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(hereinafter "Assignee") is/are desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor.

Now, therefore, be it known by all whom it may concern, that for good and valuable consideration (the sufficiency of which is hereby acknowledged) the Assignor has assigned, transferred and set over, and by these presents does assign, transfer and set over unto the said Assignee for the territory of the United States of America, the full and exclusive right, title, and interest in and to the said application and the invention embodied therein, as fully set forth and described in the specification.

A. prepared and executed on _____

B. filed in the U.S. Patent and Trademark Office under Serial No. _____

on _____ including any division, continuation, substitute or renewal application thereof; said invention, application and Letters Patent to be held and enjoyed by the said Assignee to the full end of the term for which said Letters Patent is granted, as fully and entirely as the same would have been held by the Assignor had this assignment and transfer not been made.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 21 day of

Jan 20 06

WITNESS:

INVENTOR(S):

Katsuhiko Murayama

Katsuhiko Murayama

(Name of Assignor)

(Signature of Assignor)

(Name of Assignor)

(Signature of Assignor)

(Name of Assignor)

(Signature of Assignor)

(Name of Assignor)

(Signature of Assignor)

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